

REMARKS

Claims 1 and 13-14 have been amended. No claims have been canceled. No new claims have been added. Claims 8 and 18-59 have been withdrawn. Claims 1-7 and 9-17 are pending.

Claims 1, 3-5, and 9-10 stand rejected under 35 U.S.C. § 102(b) as being clearly anticipated by Shichi (Japanese Publication JP 406151977A). Claim 2 stands rejected under 35 U.S.C. § 103(a) as being unpatentable over Shichi. Claims 6-7 and 16 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Shichi in view of Sasano (U.S. Patent No. 6,313,525). These rejections are respectfully traversed.

The Office Action includes a copy of the Japanese language version of the Shichi reference and a corresponding English language Abstract. If the Examiner intends to continue to rely upon the Shichi reference, it is respectfully requested that the Examiner obtain and send with the next Office Action, an English language translation of the entire Shichi reference.

Claim 1 recites, *inter alia*, “a frame defining an opening between a top surface and a bottom surface, said bottom surface including an indented area where a thickness between the top surface and the bottom surface is thinner than in a non indented area of said bottom surface, said frame being adapted to accept in said indented area an integrated circuit while preserving a portion of said opening between said indented area and said stop surface.”

Claim 13 recites, *inter alia*, “a packaging portion having a frame defining an opening between a top surface and a bottom surface, said bottom surface comprising: ... a second bottom surface ... mutually having a metal contact ... adapted to connect to an

integrated circuit disposed within said inward facing surface while preserving a portion of said opening above said integrated circuit."

Shichi discloses a water resistant semiconductor optical device. Fig. 1 illustrates an optical device 25 which is die-bonded and mounted on wiring 23a, 24a in a recessed portion 22 of a resin substrate 21. A transparent resin 26 further fills the space between the recess 22 and a top portion of the resin substrate 21. The resulting device is then made water resistant by an injection molding process which fills the recess 22 using a moisture resistant resin 27. The moisture resistant resin 27 is also attached to the top surface to seal the transparent resin 26 and the upper portion of the resin substrate 21.

Shichi therefore fails to disclose or suggest "a frame defining an opening between a top surface and a bottom surface, said bottom surface including an indented area where a thickness between the top surface and the bottom surface is thinner than in a non indented area of said bottom surface, said frame being adapted to accept in said indented area an integrated circuit while preserving a portion of said opening between said indented area and said stop surface" (as recited by claim 1) or "a packaging portion having a frame defining an opening between a top surface and a bottom surface, said bottom surface comprising: ... a second bottom surface ... mutually having a metal contact ... adapted to connect to an integrated circuit disposed within said inward facing surface while preserving a portion of said opening above said integrated circuit" (as recited by claim 13).

The Office Action additionally cites to Sasano, which discloses a hollow package. However, Sasano also fails to disclose or suggest the above quoted portions of independent claims 1 and 13.

Claim 1 and 13 are believed to be allowable over the prior art of record. The dependent claims, i.e., claims 2-7, 9-12, and 14-17) are also believed to be allowable for at least the same reasons as the independent claims.

In view of the above amendment, applicant believes the pending application is in condition for allowance.

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Respectfully submitted,

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